

FPGA Cyclone® II Family 4608 Cells 402.58MHz 90nm Technology 1.2V

Manufacturers	Altera Corporation (Intel)
Package/Case	FBGA-256
Product Type	Programmable Logic ICs
RoHS	Rohs
Lifecycle	



Images are for reference only

Please submit RFQ for EP2C5F256C8N or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

General Description

EP2C5F256C8N is a model number that appears to refer to a specific field-programmable gate array (FPGA) device from the Altera (now Intel) Cyclone II family of FPGAs.

Features

- FPGA type: Cyclone II
- Logic elements (LEs): 5,184
- Embedded multipliers: 18x18-bit
- Embedded memory: 262,144 bits (256 kilobits)
- Maximum user I/O pins: 266
- Clock networks with global and regional clock pins
- Various I/O standards supported, such as LVDS, LVTTTL, and SSTL
- Configuration: SRAM-based or JTAG-based
- Package type: 256-ball FineLine BGA (Ball Grid Array)

Application

- Industrial control systems
- Communications and networking equipment
- Test and measurement instruments
- Medical equipment
- Automotive electronics
- Video and image processing
- Consumer electronics
- Military and aerospace systems



CAUTION

LEVEL

3



This bag contains
MOISTURE - SENSITIVE DEVICES
 relative humidity (RH)
 1. Shelf life in sealed bag : 36 months at < 40°C and < 90%
 2. After bag is opened, devices that will be subjected to
 convection reflow, or equivalent processing (peak package body
 temperature of 260 °C) must be :

3. Devices require baking before mounting if :
 - a) Mounted within: 168 hours at factory conditions of < 30°C / 60% RH, or
 - b) Stored at < 10% RH
4. Humidity Indicator card show humidity > 10% when measured at 23 ± 5°C, or
 - a) If baking is required, devices may be baked for :
 - a) 12 hours at 125°C +/- 5°C for high temp. device containers.
 - b) Baking at 40°C + 5°C / - 0°C and < 5% RH for low temperature device containers is **NOT RECOMMENDED**

Bag Seal Date (MM - DD - YY) : 01 - 04 - 2011

Note : LEVEL defined by IPC/JEDEC J - STD - 020



2nd Level Interconnect

1. RoHS Compliant - Category: e1
 2. Maximum safe rework temperature: 260 °C
- For Rework: mount within 8 hours at factory conditions of < 8°C / 60%RH

ALTERA
 ORIGIN : KOREA
 PART # : EP2C5F256C8N
 LOT # : VBD9Y49353
 FAC # : 1013315400
 D/C : K CBD9Y1049A

TRACE CODE: 3P1KA0Z0J
 QTY : 540
 PK : p3

010411 1:38



Box Id: 383GD7Z614

CAUTION
This bag contains
MOISTURE SENSITIVE DEVICES

LEVEL **3**

1. Shelf life in sealed bag : 36 months at < 40 °C and < 90% relative humidity (RH)
2. After bag is opened, devices that will be subjected to convection reflow, or equivalent processing, (leak package body temperature of 260 °C) must be stored at factory conditions of ± 30 °C / 60%RH
a) Mounted within 168 hours RH, or b) Stored at < 10% RH
3. Devices require baking before mounting it :
a) Humidity indicator card show humidity > 10% when measured at 23 ± 5°C, or b) Condition 2a or 2b is not met.
4. If baking is required, devices may be baked for :
a) 12 hours at 125 °C +/- 5°C for high temp. device containers.
b) Baking at 40 °C + 5 °C / - 0 °C and < 5% RH for low temperature device containers is **NOT RECOMMENDED**.

Bag Seal Date (MM-DD-YY) : 05-17-11
Note: LEVEL defined by IPC/JEDEC J-STD-020

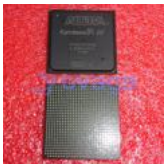
Pb
2nd Level Interconnect

1. ROHS Compliant - Category e1
2. Maximum safe rework temperature 260 °C
For Rework: mount within 8 hours at factory conditions of ≤ 30 °C / 60% RH

ALTERA Origin: KOREA PK: P3

Part # EP2C5F256C8N
Lot #: VBD9Y51167
FAC#: 1040838800
D/C: K C8D9Y11T9A
Trace Code: 3P1KA1J0J Qty: 540
Box Id: 383GD7Z614

Related Products



[EP4CE55F29C8N](#)

Altera Corporation (Intel)
FBGA-780



[EPM240M100C5N](#)

Altera Corporation (Intel)
BGA-100



[EPM1270T144A5N](#)

Altera Corporation (Intel)
TQFP-144



[EPM570F256C5N](#)

Altera Corporation (Intel)
FBGA-256



[EP2C35F672C8N](#)

Altera Corporation (Intel)
FBGA-672



[EPM7128AETC100-10](#)

Altera Corporation (Intel)
TQFP-100



[EP2C35F484C7N](#)

Altera Corporation (Intel)
FBGA-484



[EP2C35F484I8N](#)

Altera Corporation (Intel)
FBGA-484